

# **Data sheet**

SAW Rx filter
L Band

Part number: B8844

Ordering code: B39152B8844P810

Date: June 23, 2020

Version: 2.5

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## 1 Application

- Low-loss Rx filter for L band
- L Band: 1474 MHz (pass band 44 MHz)
- Usable pass band width 44MHz
- Impedance at input and output  $50\Omega$
- Very low insertion attenuation
- Unbalanced to unbalanced operation

#### 2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

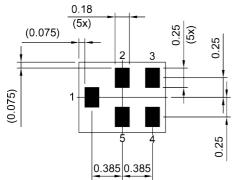


**Figure 1:** Picture of component with example of product marking.

# 3 Package

**Europe GmbH** 

#### **BOTTOM VIEW**



Pad and pitch tolerance ±0.05

# Pin configuration

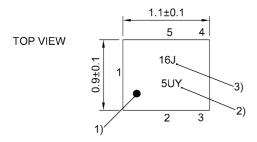
■ 1 Input

■ 4 Output

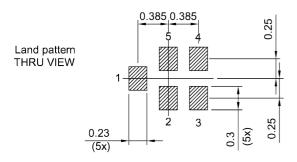
■ 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 19).



# 5 Matching circuit

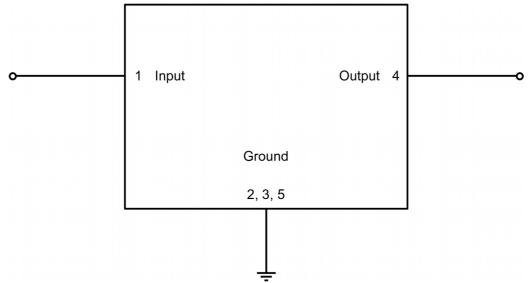


Figure 3: Schematic of matching circuit. No external matching components required.



# 6 Characteristics

**Europe GmbH** 

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

 $\begin{array}{lll} \text{Input terminating impedance} & Z_{_{\rm IN}} & = 50 \ \Omega \\ \text{Output terminating impedance} & Z_{_{\rm OUT}} & = 50 \ \Omega \\ \end{array}$ 

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	1474	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	1452 1496	MHz		_	1.7	2.3	dB
Amplitude ripple (p-p)			Δα				
	1452 1496	MHz		_	0.6	1.2	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	1452 1496	MHz		_	1.6	2.0	
@ output port	1452 1496	MHz		_	1.6	2.0	
Maximum error vector magnitude			$EVM_{max}^{1}$				
	1454.4 1493.6	MHz		_	1.5	3.0	%
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	800 915	MHz		48	58	<u> </u>	dB
	1530 1570	MHz		20	32	<u> </u>	dB
	1574 1577	MHz		40	54	<u> </u>	dB
	1710 1785	MHz		46	54	_	dB
	1850 1910	MHz		46	52	_	dB
	1920 1980	MHz		46	52	_	dB
	2500 2570	MHz		42	47	_	dB
	5000 7000	MHz		30	37	_	dB

<sup>1)</sup> Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



**Europe GmbH** 

## 7 Maximum ratings

Operable temperature	T <sub>OP</sub> = −40 °C +85 °C	
Storage temperature	T <sub>STG</sub> <sup>1)</sup> = -40 °C +85 °C	
DC voltage	$ V_{DC} ^{2)} = 0 \text{ V}$	
ESD voltage		
	V <sub>ESD</sub> <sup>3)</sup> = 50 V	Machine model.
	V <sub>ESD</sub> <sup>4)</sup> = 150 V	Human body model.
	V <sub>ESD</sub> <sup>5)</sup> = 600 V	Charged device model.
Input power	P <sub>IN</sub>	
@ input port: 832 862 MHz	30 dBm <sup>6)</sup>	Continuous wave for 10000 h @ 85 °C.
@ input port: 1452 1496 MHz	16 dBm <sup>6)</sup>	Continuous wave for 10000 h @ 85 °C.
@ input port: 1710 1785 MHz	26 dBm <sup>6)</sup>	Continuous wave for 10000 h @ 85 °C.
@ input port: 1920 1980 MHz	30 dBm <sup>6)</sup>	Continuous wave for 10000 h @ 85 °C.
@ input port: 2500 2570 MHz	30 dBm <sup>6)</sup>	Continuous wave for 10000 h @ 85 °C.

Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.

<sup>&</sup>lt;sup>3)</sup> According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

<sup>&</sup>lt;sup>4)</sup> According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

<sup>&</sup>lt;sup>5)</sup> According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

<sup>&</sup>lt;sup>6)</sup> Expected Life Time according to accelerated power durability simulation and wear out models.

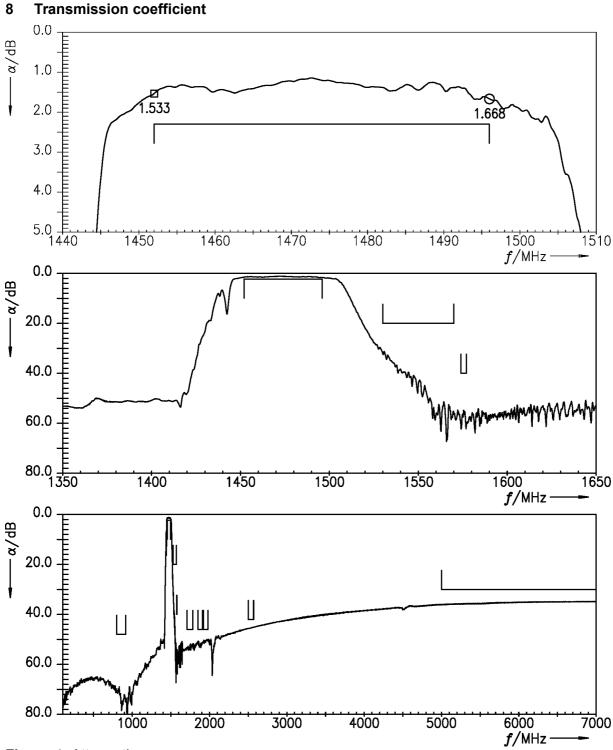
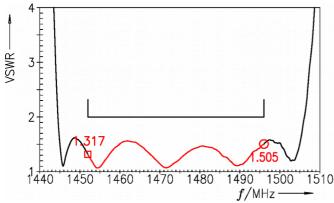


Figure 4: Attenuation.



### 9 Reflection coefficients



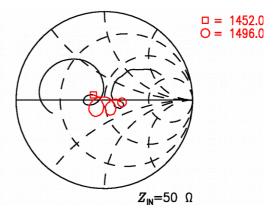
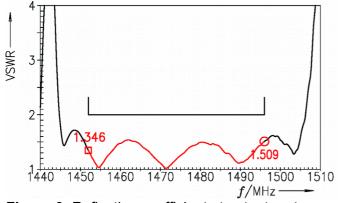


Figure 5: Reflection coefficient at input port.



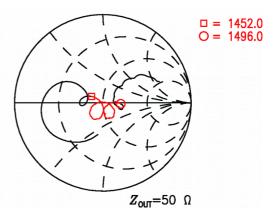


Figure 6: Reflection coefficient at output port.

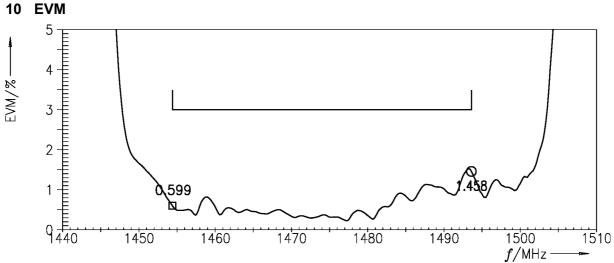
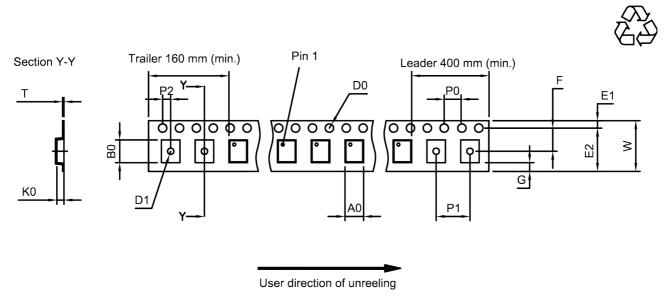


Figure 7: Error vector magnitude.



# 11 Packing material

## 11.1 Tape



**Figure 8:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	1.02±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	2.0±0.1 mm
B <sub>0</sub>	1.22±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.55±0.05 mm	G	_	T	0.25±0.03 mm
D <sub>1</sub>	0.55±0.1 mm	K <sub>0</sub>	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75 <sub>±0.1</sub> mm	P <sub>0</sub>	4.0±0.1 mm		

Table 1: Tape dimensions.

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#### 11.2 Reel with diameter of 180 mm

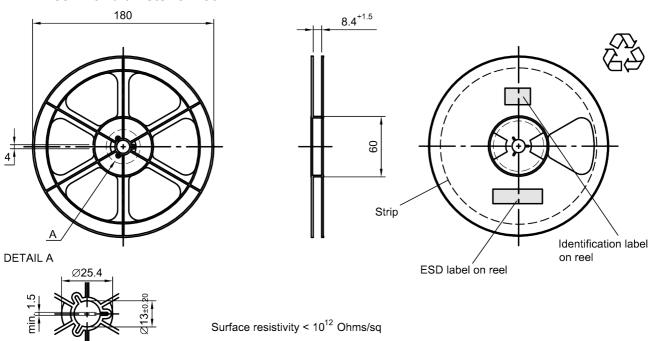


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

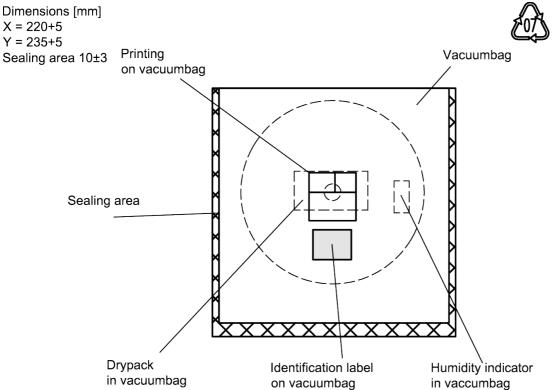


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

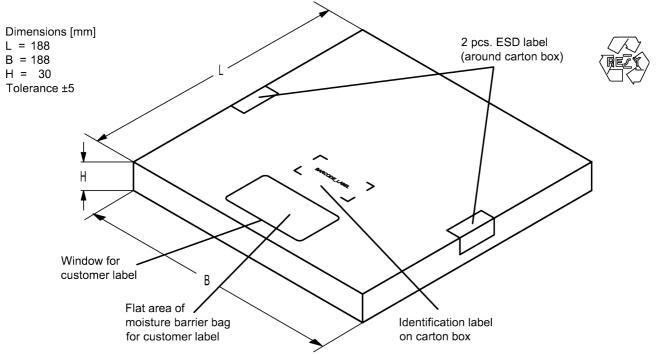


Figure 11: Drawing of folding box for reel with diameter of 180 mm.

### 11.3 Reel with diameter of 330 mm

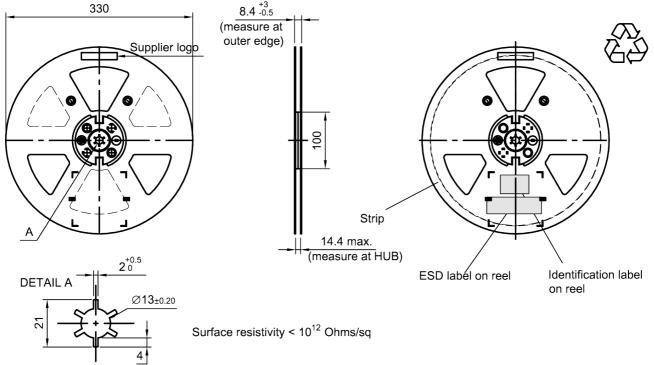


Figure 12: Drawing of reel (first-angle projection) with diameter of 330 mm.

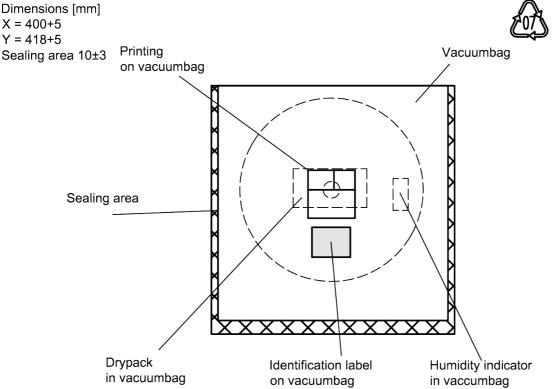


Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

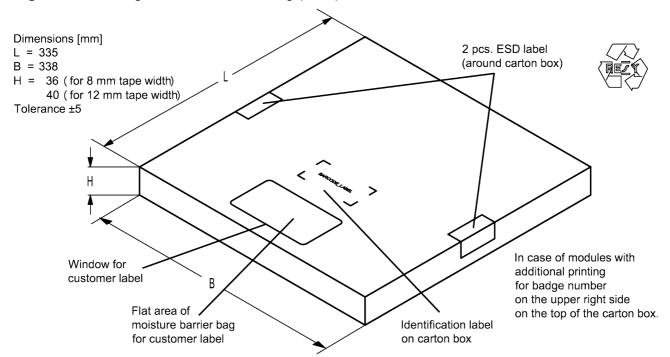


Figure 14: Drawing of folding box for reel with diameter of 330 mm.



## 12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

## ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B8844 is 8MC.

#### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345  $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  12345

Adopted BASE32 code for type number			
Decimal	Base32	Decimal	Base32
value	code	value	code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	Α	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number					
Decimal	Base47	Decimal	Base47		
value	code	value	code		
0	0	24	R		
1	1	25	S		
2	2	26	Т		
3	3	27	U		
4	4	28	V		
5	5	29	W		
6	6	30	Х		
7	7	31	Y		
8	8	32	Z		
9	9	33	b		
10	Α	34	d		
11	В	35	f		
12	С	36	h		
13	D	37	n		
14	E	38	r		
15	F	39	t		
16	G	40	V		
17	Н	41	\		
18	J	42	?		
19	K	43	{		
20	L	44	}		
21	М	45	<		
22	N	46	>		
23	Р				

**Table 2:** Lists for encoding and decoding of marking.

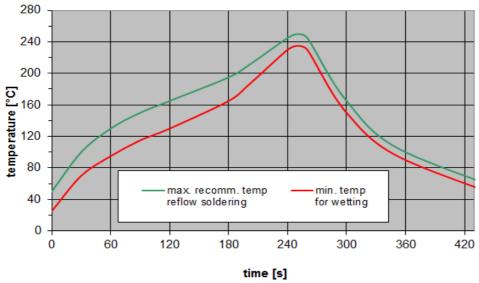


## 13 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature $T_{\text{peak}}$	250 °C +0/-5 °C
wetting temperature $T_{\min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 15:** Recommended reflow profile for convection and infrared soldering – lead-free solder.



#### 14 Annotations

#### 14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 14.3 Ordering codes and packing units

Ordering code	Packing unit
B39152B8844P810	15000 pcs
B39152B8844P810S 5	5000 pcs

Table 4: Ordering codes and packing units.



#### 15 Cautions and warnings

## 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://rffe.gualcomm.com/">https://rffe.gualcomm.com/</a>.

#### 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

#### 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

#### 15.4 Package information

## Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



#### 16 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (<a href="https://rffe.qualcomm.com">https://rffe.qualcomm.com</a>). Should you have any more detailed questions, please contact our sales offices.
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